

JPCA Show

51st International Electronic
Circuits Exhibition

JIEP Microelectronics Show

36th ADVANCED ELECTRONICS
PACKAGING EXHIBITION

**JISSO
PROTEC**

23rd Jissin Process Technology
Exhibition

SDGs デバイス展
SDGs Device Show

WIRE Japan Show
Electrical
/optical transmission technology Exhibition

JEP/TEP Show
Japan Federation Of Electronic Parts Distributors And Dealers
Tokyo Electronics Appliances Wholesalers Association

E-Textile
E-Textile

Smart Sensing
Smart Sensing

INTERNATIONAL OPTOELECTRONICS EXHIBITION
interOpto
interOpto

LED JAPAN
LED JAPAN

Imaging Japan
Imaging Japan

Edge Computing
Edge Computing

One Step into the Future

See. Face. Talk.



The Exhibition Guide

2022. 6.15_{Wed.} → 6.17_{Fri.}

Tokyo Big Sight East Exhibition Halls

**The Total Solution Exhibition
for Electronic Equipment 2022**

www.jpccashow.com



Official Website

Applications will be accepted from January 17, 2022 (Mon.) 10:00 a.m. (JST)

Organizers: Japan Electronics Packaging and Circuits Association,
Japan Institute of Electronics Packaging, Japan Robot Association
Co-organizers: Electronic Device Industry News (Sangyo Times, Inc.), Electric Wire & Cable News (KOGYO TSUSHIN CO., LTD.),
JTB Communication Design, Inc.,
Japan Federation Of Electronic Parts Distributors And Dealers
Tokyo Electronics Appliances Wholesalers Association
SENKEN SHIMBUN CO., LTD., Optoelectronics Industry and Technology Development Association
Sponsor: Ministry of Economy, Trade and Industry

Overseas Cooperation:
World Electronic Circuits Council (WECC) Member Associates:
China Printed Circuit Association (CPCA),
European Institute of Printed Circuits (EIPC),
Hong Kong Printed Circuit Association (HKPCA),
IPC-Association Connecting Electronics Industries (IPC), Indian Printed Circuit Association (IPCA),
Electronic Industries Association of India (ELCINA), Korea Printed Circuit Association (KPCA),
Thailand Printed Circuit Association (THPCA),
Taiwan Printed Circuit Association (TPCA)

As of Dec. 15, 2021

Comprehensive exhibition of technology embodying 5G/5G+, automobile, IoT/infrastructure (network, reusable energy, data center, etc.), robots, wearable, advanced optical system, etc.

- Highly specialized and focused
- Exhibition of large attendance from all over the world

Exhibition Outline

Our objective is to offer and propose technical information and contribute to the advancement of the electronic circuit industry and all related fields by presenting exhibitions of new contents and solutions related to the electronic circuits and packaging technologies used in all electronic / information and communication / control equipments, as well as sensors and E-Textiles (wearable technology) which have great potential for widespread use.

Exhibition Period	Wednesday, June 15 to Friday, June 17, 2022, 10:00 a.m. - 5:00 p.m.
Venue	Tokyo Big Sight East Exhibition Halls 2-6
Managed by	Japan Electronics Packaging and Circuits Association (JPCA)
Secretariat Office	JTB Communication Design, Inc.
Admission	1,000 Yen (including tax) * Free Admission for those who have pre-registered online.

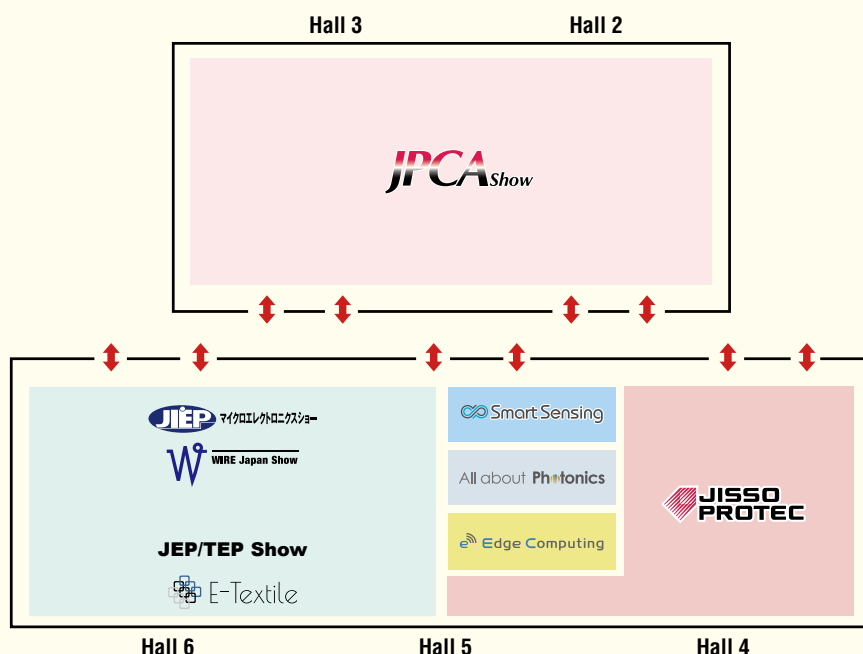
Result of 2021

Venue	Tokyo Big Sight South Hall 1-3+Conference Tower		
Exhibit scale	228 companies / 411 booths	Number of visitors	16,699 people







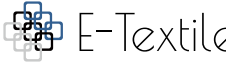





Key points of the 2022 Exhibition!

- (1) Same exhibition floor size as before COVID (over 40,000 sq.m.)
- (2) Exhibitors can choose their own booth (in order of application)
- (3) Strengthen the effect of exhibiting (Webinars, digest of exhibition)
- (4) New SDGs Device Exhibition

Tentative Exhibition Floor Layout



Exhibitions held inside the exhibition/relevant exhibits

<div>Electronic circuits technology</div> <div><p>51st International Electronic Circuits Exhibition</p></div> <div><ul style="list-style-type: none">● PWB Tech Finished Products, Design Technologies, Reliability and Inspection Technologies, Main Materials, Processing Technologies, Materials, and Equipment, Manufacturing Equipment, Environmental Systems, Distribution Systems● Module JAPAN Module board / Module Board mounting / General technology for built-in parts (Finished Products / Related Products / Design / Reliability inspection / Materials/Functional materials / Related equipment / Related system)● Flexible Printed Circuits Products Area General technology for Flexible Printed Circuits (Manufacturing)● EMS Japan General contracted services related to EMS, Electronic electrical equipments, and Semiconductors<p>Organizer: Japan Electronics Packaging and Circuits Association</p></div>	<div>High-density packaging technologies</div> <div><p>Microelectronics Show</p></div> <div><p>36th ADVANCED ELECTRONICS PACKAGING EXHIBITION</p><p>General technology for implementation and electric technology (Materials / Circuit and Mounting design / High speed high frequency / Electromagnetic properties / Electronic parts / mounting / Optical circuit mounting / Environmental affinity implementation / Semiconductor Package / Micro mechatronics mounting technology / Related Manufacturing equipment)</p><p>Organizer: Japan Institute of Electronics Packaging</p></div>	<div>Electronic Component Packaging Technologies</div> <div><p>JISSO PROTEC</p></div> <div><p>23rd Jisso Process Technology Exhibition</p><p>General technology for Electronic Component Packaging Technologies (Electronic component mounting machine / Semiconductor mounting equipment System / inspection technology / Mounting design system / Robots)</p><p>Organizer: Japan Robot Association</p></div>	
<div>SDGs Materialization Technology</div> <div><p>SDGs Device Show</p></div> <div><ul style="list-style-type: none">• Renewable energy related electronics• Power electronics related mounting / materials• Power semiconductors / power devices (IGBTs, MOSFETs, Bipolar transistor, etc.), various memories (S-RAM, D-RAM, etc.), semiconductor package, module with built-in parts, metal core printed wiring board, thermal solution, Solar cell batteries, batteries, hydrogen fuel, power electronics, various related devices, etc.<p>Co-organizers: Japan Electronics Packaging and Circuits Association, Electronic Device Industry News (Sangyo Times, Inc.)</p></div>	<div>Electrical/optical transmission technology</div> <div><p>WIRE Japan Show</p><p>Electrical /optical transmission technology Exhibition</p></div> <div><p>General transmission technology for using wire and cable (Industrial equipment / Electrical wire, cable and connector / Electric wire processing machine / Wiring material / Wire Harness / Measuring instrument for electric wire and cable / Various devices + D116 / Inspection technology / M2M transmission / Optical transmission)</p><p>Co-organizers: Japan Electronics Packaging and Circuits Association, Cable News (KOGYO TSUSHIN CO., LTD)</p></div>	<div>Semiconductors and Electronic parts</div> <div><p>JEP/TEP Show</p><p>Japan Federation Of Electronic Parts Distributors And Dealers Tokyo Electronics Appliances Wholesalers Association</p></div> <div><p>General technology for solutions by Semiconductors and Electronic parts (Semiconductors / Electronic Devices / Sensors / Mechanical Devices / FA control equipments / Measuring instruments / Power Sources / IoT and M2M Solution / Manufacturing solution system)</p><p>Co-organizers: Japan Federation Of Electronic Parts Distributors And Dealers, Tokyo Electronics Appliances Wholesalers Association</p></div>	<div>Highly functional textile</div> <div><p>E-Textile</p></div> <div><p>A mix e-textile of electronic technology, fiber and clothing (General technology for smart textile, stretchable and wearable (Textile material / Conductive material / material / Knitting / weaving technology / Print marking technology / Films)</p><p>Co-organizers: Japan Electronics Packaging and Circuits Association, SENKEN SHIMBUN CO., LTD.</p></div>
<div>Sensor technology</div> <div><p>Smart Sensing</p></div> <div><p>General technology for Sensor and Sensing System (Sensors, Sensor Nodes, Semiconductors, Parts and Devices, Electronics, Telecommunications Devices, Network Systems, Software, Data Platform, Power Sources, Other Related Devices, Technologies and Services)</p><p>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p></div>	<div>Edge solution technology</div> <div><p>Edge Computing</p></div> <div><p>Advantageous general edge solutions for areas such as low delay, high safety and low communication volume [Edge Application Areas] Automatic operation system / Factory Automation / Telemedicine / AR/VR / Smart city / Agritech / FinTech / Unmanned store, etc.</p><p>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</p></div>	<div>All about Photonics</div> <div><div><div>Optical and next-generation applications / network systems</div><div><p>interOpto</p></div><div>Optical devices for Automotive and in-vehicle / Manufacturing and production systems / Data centers / Long-distance communication / Healthcare and medical optical devices / AV and home appliances</div><div>Organizer: Optoelectronics Industry and Technology Development Association (OITDA) Presented by: JTB Communication Design, Inc.</div></div><div><div>Deep UV / NIR / LEDs application development</div><div><p>LED JAPAN</p></div><div>UV / NIR LEDs / LED package material / Devices / power sources / Measurement / inspection / manufacturing equipment / Optical component / material / LED application finished product (automotive lighting, LED visible light communication, medical lighting)</div><div>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</div></div><div><div>Image processing / sensing technology</div><div><p>Imaging Japan</p></div><div>Various camera / sensor equipments / Image processing equipment / Image recognition / image understanding technology / Instrumentation / measurement technology / LiDAR</div><div>Co-organizers: Japan Electronics Packaging and Circuits Association, JTB Communication Design, Inc.</div></div></div>	

Companies in each field that are expected to participate

● Related to automobile:

Aisin Seiki, Asahi Denso, ICHIKOH INDUSTRIES, Calsonic Kansei, Keihin, KOA, KOITO MANUFACTURING, STANLEY ELECTRIC, Sumitomo Wiring Systems, DAIHATSU MOTOR, DENSO, TOKAI RIKI, Toyodenso, TOYOTA MOTOR, NISSAN MOTOR, NHK SPRING, PIONEER, Hitachi Automotive Systems, Hino Motors, SUBARU, Honda Motor, Mazda Motor, MITSUBISHI MOTORS, YAZAKI

● OA/Robotics:

OMRON, KEYENCE, Canon, KONICA MINOLTA, CYBERDYNE, SANYO DENKI, JUKI, SEIKO EPSON, Panasonic, Panasonic Smart Factory Solutions, FANUC, FUJII, Fuji Xerox, Mitsubishi Electric, YASKAWA Electric, Yamaha Motor, Ricoh Industry, RICOH JAPAN

● Related to information and communication:

Apple, Intel, NHK Media Technology, NTT, NTT DOCOMO, Oki Electric Industry, Korean Broadcasting System (KBS), KYOCERA, KDDI, SoftBank, TOKYO BROADCASTING SYSTEM HOLDINGS (TBS), Toshiba Information Systems (Japan), IBM Japan, NEC, Microsoft Japan, Nihon Unisys, Panasonic, PFU, Hitachi, Huawei, Fujikura, FUJITSU, Murata Manufacturing

● Related to AV and home electrical appliances:

LG Electronics, CASIO COMPUTER, Canon, Samsung Electronics, Sharp, Sony, Sony Global Manufacturing & Operations, Sony Semiconductor Solutions, DAIKIN INDUSTRIES, NIKON, PIONEER, Panasonic, FUJITSU GENERAL, YAMAHA, Roland

Related to medical equipment:

Olympus, Siemens, SHIMADZU, SHIRAKAWA OLYMPUS, Terumo, Canon Medical Systems, Hitachi High-Technologies, Hitachi Healthcare Manufacturing, Fujifilm, MARK ELECTRONICS, MORITA TOKYO MFG

● Related to semiconductor device

Intel, STMicroelectronics, Canon, Samsung Electronics, SCREEN Holdings, Sony, TDK, Tokyo Electron, Toshiba Memory, NIKON, Hitachi High-Technologies, FUJITSU SEMICONDUCTOR, Micron Japan, Renesas Electronics, ROHM

● Related to aerospace:

IHI, NEC Space Technologies, JAXA (Japan Aerospace Exploration Agency), SINFONIA TECHNOLOGY, Nabtesco, Nippon Avionics, NEC, Mitsubishi Heavy Industries, Mitsubishi Electric

● Optical technology:

Dai Nippon Printing Co., Ltd., Toppan Printing CO., LTD., HOYA CORPORATION, Hamamatsu Photonics K.K., Sumitomo Electric Industries, Ltd., Yokogawa Electric Corporation, LIXIL Corporation, Azbil Corporation, NGK ELECTRONICS DEVICES, INC., NTT Electronics Corporation, KAGA ELECTRONICS CO.,LTD., JVCKENWOOD Corporation, HP Japan Inc., IHI Inspection & Instrumentation Co., Ltd., DISCO Corporation, ALPS ALPINE CO., LTD., CANON MEDICAL SYSTEMS CORPORATION, Sony Imaging Products & Solutions Inc., SEKISUI CHEMICAL CO., LTD., SIGMAKOKI CO.,LTD., Sharp Fukuyama Laser Co., Ltd., NGK INSULATORS, LTD., Nippon Sheet Glass Co., Ltd.

● Other:

Japan Maritime Self-Defense Force, Japan Ground Self-Defense Force, Tokyo Gas, Tokyo Electric Power, Central Japan Railway, WEST JAPAN RAILWAY, East Japan Railway, Mizuho Bank

● Electronic circuit board:

ADVANTEST, Eastern, IBIDEN, ELNA, Kyoei Sangyo, KYOSHA, KYOCERA, Kyoden, Shirai Electronics Industrial, SHINKO, SHINKO ELECTRIC INDUSTRIES, Sumitomo Electric Printed Circuits, DAISHO DENSHI, Nitto Denko, CMK, NIPPON MEKTRON, Panasonic, Hitachi Chemical, Fujikura, FUJITSU INTERCONNECT TECHNOLOGIES, Meiko Electronics, Yamashita Materials, RISHO KOGYO

Exhibition Fee

Category	1 booth/9m ² *Tax included
Non-Members	Yen 451,000
Members	Yen 385,000

*1 Members of the WECC member associations

(CPCA, EIPC, ELCINA, HKPCA, IPC, IPCA, KPCA, THPCA, TPCA.)

* Size of a booth is 9m² (3m × 3m).

* Booth construction, cleaning, electricity, water Supply, etc. is not included in the exhibition fee.

How to apply (From January 17, 2022 (Mon.) 10:00 a.m. (JST))

Please apply online on our website. (www.jpccashow.com)

Applications will be accepted from January 17, 2022 (Mon.) 10:00 a.m. (JST).

If you use the Application Form, please apply by e-mail or FAX.

Please select the exhibition based on your products, technologies or services and carefully read the "Exhibition Regulations" on the back of the Application Form.

For the exhibition which has the exclusive application form, the relevant exhibition regulations shall be applied.

We will send you an invoice after receiving the Application Form, so please transfer the fee to our account by the due date noted on the invoice (In principle, transfer before the exhibition). The invoice can be downloaded from the exhibitor portal.

Deadline

Friday, March 11, 2022

If all spaces are reserved before the deadline, the application will no longer be accepted.

Cancellation charges

If an exhibit is cancelled to suit the exhibitor's circumstances, cancellation charges (full or partial fees) shall apply as below.

Date of receipt of written notice of cancellation	Cancellation charges
Until Friday, March 11, 2022	30% of booth fees
Saturday, March 12 – Wednesday, April 13, 2022	50% of booth fees
Thursday, April 14 – Wednesday, May 11, 2022	70% of booth fees
From Thursday, May 12, 2022 onward	100% of booth fees

Schedule prior to the Exhibition (Tentative)

January	March	April	June
<p>▲</p> <p>January 17 (Fri.) 10:00 – Exhibition application begins</p>	<p>▲</p> <p>March 11 (Fri.) Exhibitor application deadline</p> <p>▲</p> <p>Late March Exhibitor Manual available</p>	<p>▲</p> <p>Early April Booth Location Selection Meeting Exhibitor's Briefing</p> <p>▲</p> <p>Early April Sending Invitations Visitor Registration begins</p>	<p>June 13 (Mon.)-14 (Tues.) Installation period</p> <p>June 15 (Wed.)-17 (Fri.) Exhibition open</p> <p>* Immediate removal on the last day</p>
<p>← Late March onwards Submission of necessary forms →</p>			

● Safety measures and policies to be taken by organizers

We will take measures to reduce spread of COVID-19 among participants, organizers and other parties involved in the exhibition, and hold the Exhibition with attention to safety. From now on, in consideration of the policies and requests of the Japanese government, relevant ministries and agencies, and local governments, we will plan and implement the exhibition in cooperation and consultation with the facility side.

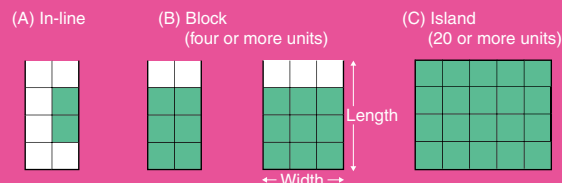
● In the event of cancellation of the Exhibition

If we decide to cancel the Exhibition due to COVID-19, we will refund the total exhibition fee. * For details, please see the Exhibition Regulations.

**Please refer to the following websites for the most recent information.

- > Border enforcement measures to prevent the spread of novel coronavirus (COVID-19) (Ministry of Foreign Affairs of Japan website): https://www.mofa.go.jp/ca/fna/page4e_001053.html
- > Situation Report in Japan (Ministry of Health, Labour and Welfare website): https://www.mhlw.go.jp/stf/covid-19/kokunainohasseijoukyou_00006.html#1-1

Booth type



*In some cases, it may not be possible to prepare the requested booth type.

*Requests for a corner booth are not accepted.

Assignment of Booth Locations

Booths will be assigned at the Booth Location Selection Meeting (scheduled for early April, 2022).

As a rule, exhibitors will be able to choose their booth locations on a first-come-first-served basis.

Details will be made available in the rules and regulations to be made public from 10:00 a.m. January 17th.

Exhibitor Support Program Option

Promotion services will provide an opportunity to increase your presence at the exhibition.

Package booth

● 1 booth / basic plan

Price: 82,500 Yen (Tax included)

This plan includes the minimum necessary booth fixtures and fittings, power supply and carpet.



Managed by

Japan Electronics Packaging and Circuits Association (JPCA)

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Official Website